

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yoshiyuki KONDO</td> <td>07/31/2013</td> </tr> <tr> <td>Koichi TANIMOTO</td> <td>07/31/2013</td> </tr> <tr> <td>Yukio TAKEUCHI</td> <td>07/31/2013</td> </tr> <tr> <td>Yusuke YANASE</td> <td>07/31/2013</td> </tr> </tbody> </table>		Name	Execution Date	Yoshiyuki KONDO	07/31/2013	Koichi TANIMOTO	07/31/2013	Yukio TAKEUCHI	07/31/2013	Yusuke YANASE	07/31/2013
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Yusuke YANASE	07/31/2013										
RECEIVING PARTY DATA											
Name:	MITSUBISHI HEAVY INDUSTRIES, LTD.										
Street Address:	16-5, Konan 2-chome, Minato-ku,										
City:	Tokyo										
State/Country:	JAPAN										
Postal Code:	108-8215										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13982864</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13982864						
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Application Number:	13982864										
CORRESPONDENCE DATA											
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NAME OF SUBMITTER:	Janae Johnson										
Signature:	/Janae Johnson/										

PATENT

Date:

07/31/2013

Total Attachments: 2

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2011-712-001
OSP-48022
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ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s) of Inventor(s) (1) Yoshiyuki KONDO; (2) Koichi TANIMOTO; (3) Yukio TAKEUCHI; and (4) Yusuke YANASE
the undersigned hereby sell(s) and assign(s) to

Insert Name(s) of Assignee(s) MITSUBISHI HEAVY INDUSTRIES, LTD.
Address of 16-5, Konan 2-chome, Minato-ku, Tokyo 108-8215 Japan
(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of Invention AUTOCLAVE AND METHOD FOR HEAT CURING MOLDED MATERIAL

Date of Signing of Application for which an application for patent in the United States has been executed by the undersigned on _____

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, D.C. 20006-1021, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date July 31, 2013, Name of the Inventor *Yoshiyuki Kondo*
Yoshiyuki KONDO

Date July 31, 2013, Name of the Inventor *Kotchi Tanimoto*
Kotchi TANIMOTO

Date July 31, 2013, Name of the Inventor *Yukio Takeuchi*
Yukio TAKEUCHI

Date July 31, 2013, Name of the Inventor *Yusuke Yanase*
Yusuke YANASE

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness _____

Witness _____

ACKNOWLEDGMENT

_____ } ss

This _____ day of _____, 20____, before me personally came the above-named me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

Official Signature

SEAL

Official Title

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date _____
Applicant Reference Number _____ Atty Docket No. _____
Title of Invention _____
